

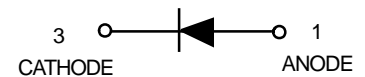
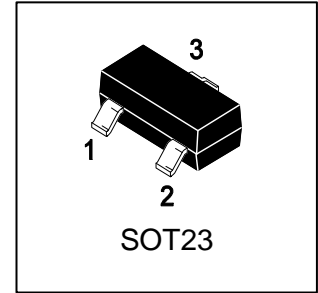
# LMBD6050LT1G

## S-LMBD6050LT1G

Switching Diode

### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



### 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMBD6050LT1G	5A	3000/Tape&Reel
LMBD6050LT3G	5A	10000/Tape&Reel

### 3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Reverse Voltage	VR	70	V
Forward Current	IF	200	mA
Peak Forward Surge Current	IFM(surge)	500	mA

### 4. THERMAL CHARACTERISTICS

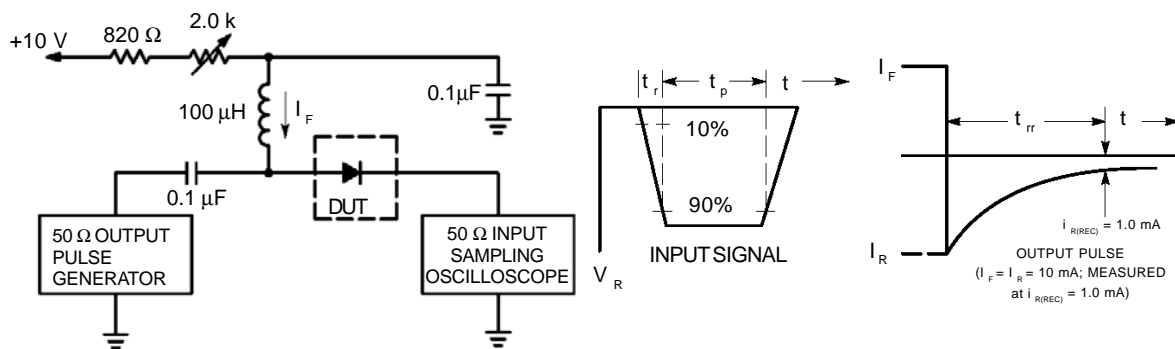
Parameter	Symbol	Value	Unit
Total Device Dissipation FR-5 Board (Note 1) TA = 25°C Derate above 25°C	PD	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient	RθJA	556	°C/W
Total Device Dissipation Alumina Substrate(Note 2) TA = 25°C Derate above 25°C	PD	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient	RθJA	417	°C/W
Junction and Storage Temperature	TJ , Tstg	-55~+150	°C

1. FR-5 = 1.0 x 0.75 x 0.062 in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

**5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)**

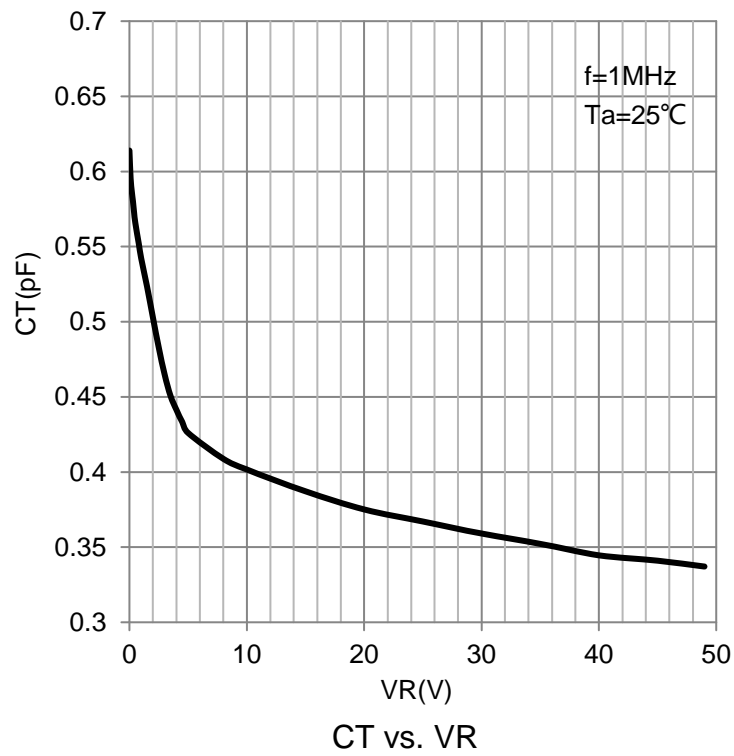
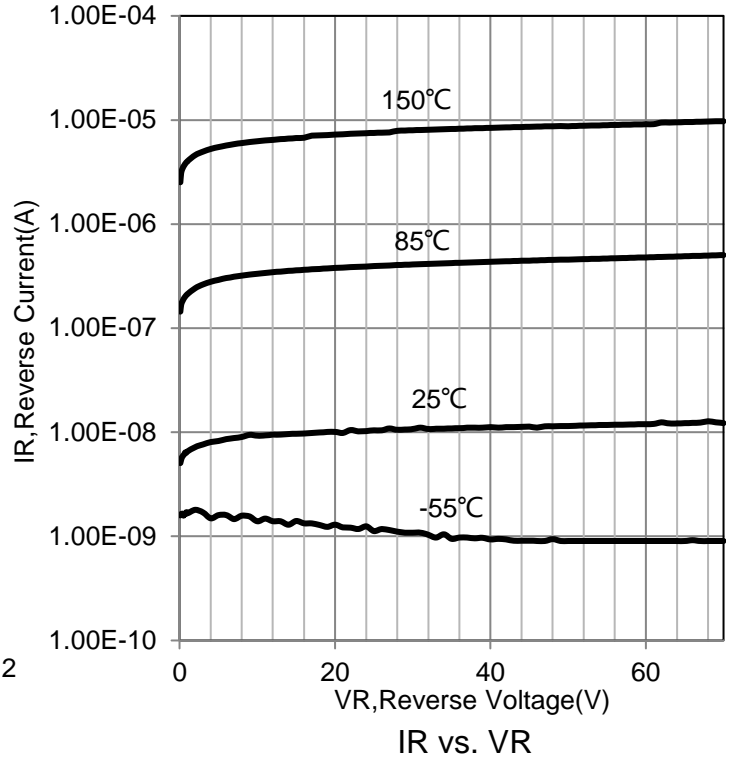
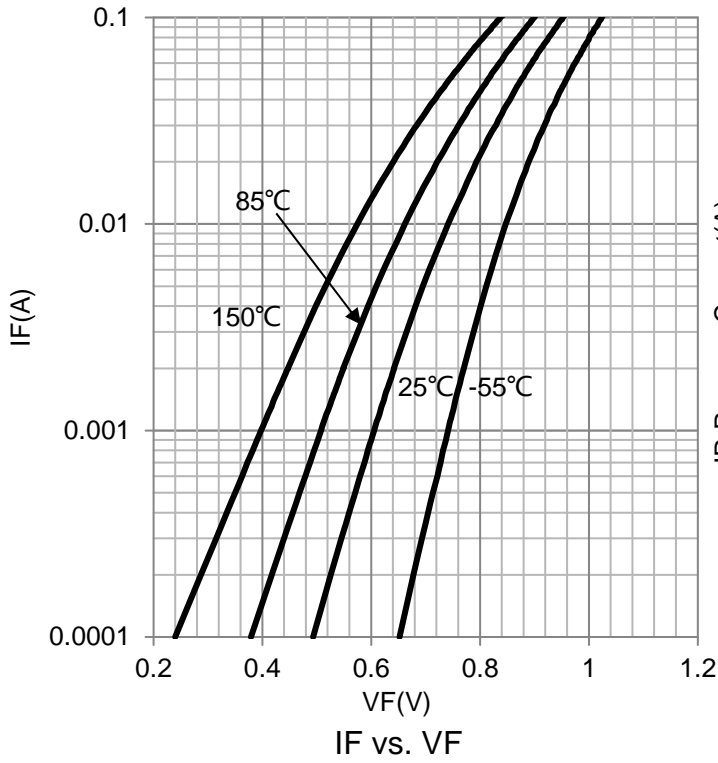
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage ( $I_{BR} = 100 \mu A$ )	V(BR)	70	-	-	V
Reverse Voltage Leakage Current ( $V_R = 50 V$ )	IR	-	-	0.1	$\mu A$
Forward Voltage ( $I_F = 1.0 mA$ ) ( $I_F = 100 mA$ )	VF	0.55 0.85	- -	0.7 1.1	V
Reverse Recovery Time ( $I_F=I_R=10mA, I_R(REC)=1.0mA$ )(Figure 1)	trr	-	-	4	nS
Capacitance( $V_R=0V$ )	C	-	-	2.5	pF



- Notes:
1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current ( $I_F$ ) of 10mA.
  2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10mA.
  3.  $t_p \gg t_{rr}$

**Figure 1. Recovery Time Equivalent Test Circuit**

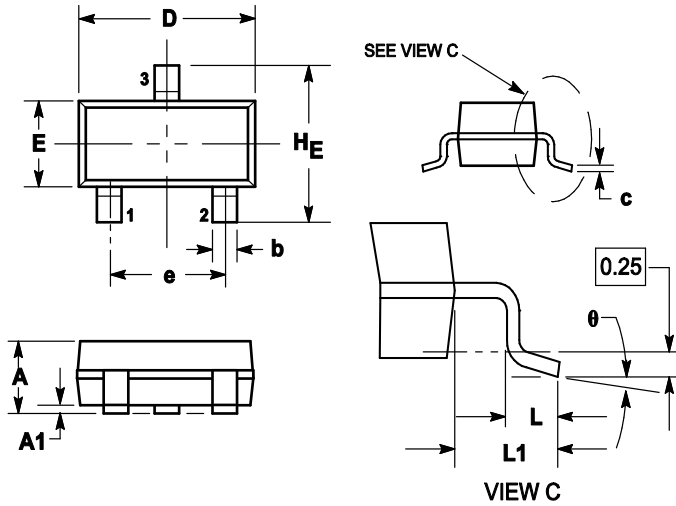
6.ELECTRICAL CHARACTERISTICS CURVES



**7.OUTLINE AND DIMENSIONS**

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

**8.SOLDERING FOOTPRINT**
